



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR PowerPAIR® 6 x 5					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	400	200 000	200 °C + N2	0	0
HAST	1347	134 700	130 °C, 85 % RH	0	0
Pressure Pot	1487	142 752	121°, 15 PSIG	0	0
Solder DUNK	235	705	260 °C, 10 s	0	0
Solderability	110	910	883 M2003	0	0
Temp. Cycle	2377	1 068 760	-55 °C to 150 °C	0	0